

ABSTRACT

This invention is an improved processing method and structure for the packaging technique of a large size field emission display. A large size field emission display includes an indium-tin oxides (ITO) conducting glass substrate, which is covered by the first screen mask and the second screen mask defined to a BM layer area, a multi-phosphor layer area and a hollow area. Each area was coated to form an Al layer, which was formed an AlO_x layer through a phosphor sintering process. The spacer was fixed in a hollow area of an AlO_x layer through an anodic assembling technique. The next plate was fixed on the spacer to accomplish an aligner process.